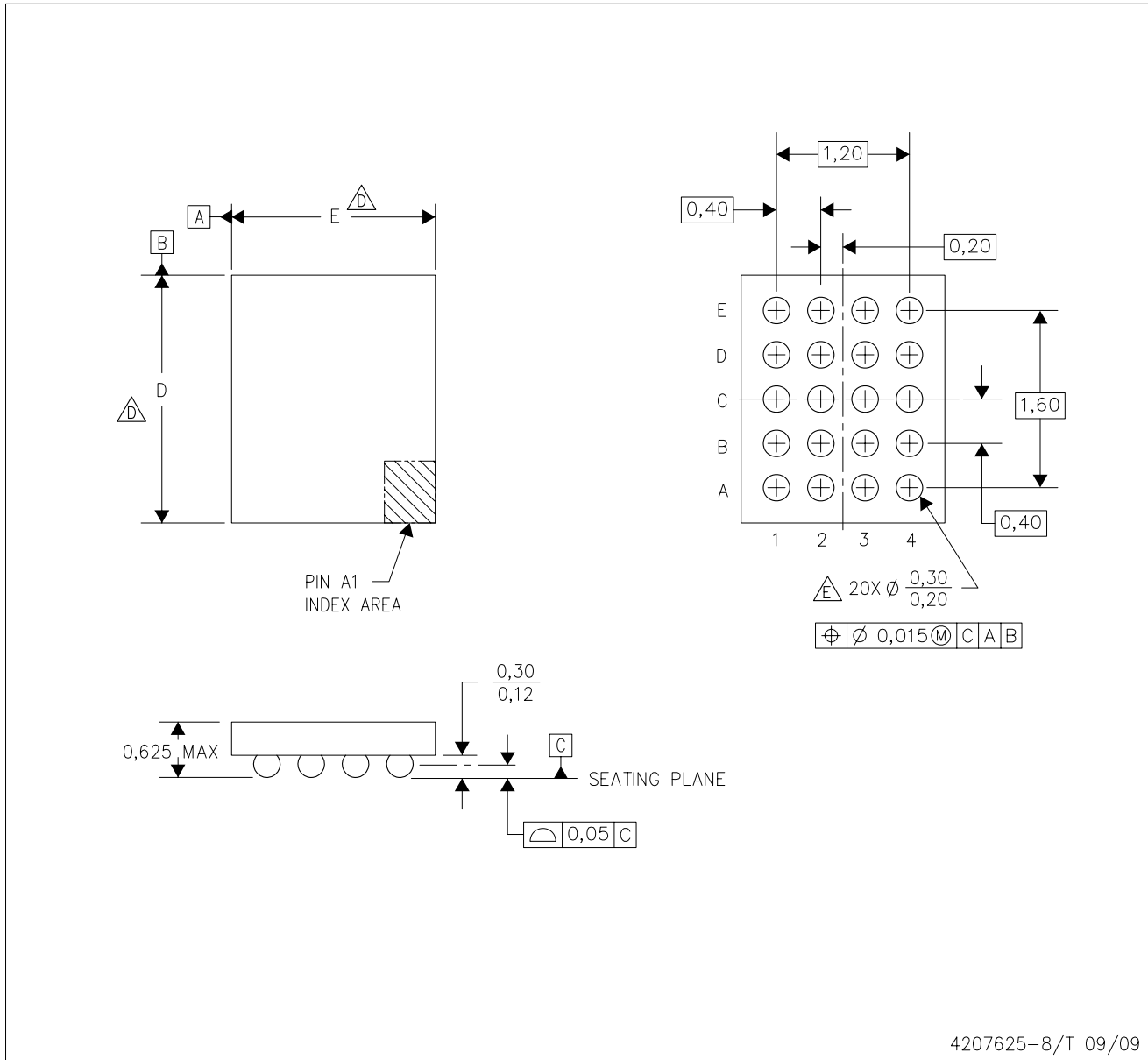


YFF (R-XBGA-N20)

DIE-SIZE BALL GRID ARRAY



4207625-8/T 09/09

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - △ Devices in YFF package can have dimension D ranging from 1.96 to 2.65 mm and dimension E ranging from 1.56 to 2.25mm. To determine the exact package size of a particular device, refer to the device datasheet or contact a local TI representative.
  - E. Reference Product Data Sheet for array population.  
5 x 4 matrix pattern is shown for illustration only.
  - F. This package contains Pb-free balls.

NanoFree is a trademark of Texas Instruments.

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